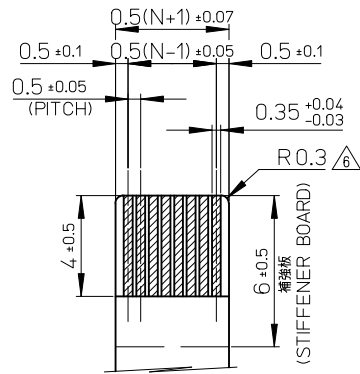


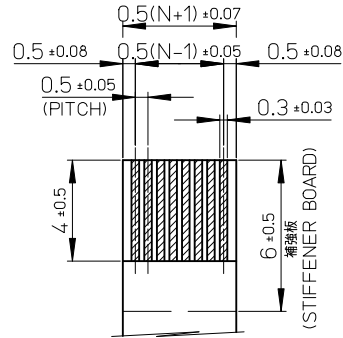
16.1	14.3	10.65	9.5	52745-2097	20
15.6	13.8	10.15	9	52745-1997	19
15.1	13.3	9.65	8.5	52745-1897	18
14.6	12.8	9.15	8	52745-1797	17
14.1	12.3	8.65	7.5	52745-1697	16
13.6	11.8	8.15	7	52745-1597	15
13.1	11.3	7.65	6.5	52745-1497	14
12.6	10.8	7.15	6	52745-1397	13
12.1	10.3	6.65	5.5	52745-1297	12
11.6	9.8	6.15	5	52745-1197	11
11.1	9.3	5.65	4.5	52745-1097	10
10.6	8.8	5.15	4	52745-0997	9
10.1	8.3	4.65	3.5	52745-0897	8
9.6	7.8	4.15	3	52745-0797	7
9.1	7.3	3.65	2.5	52745-0697	6
8.1	6.3	2.65	1.5	52745-0497	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**59

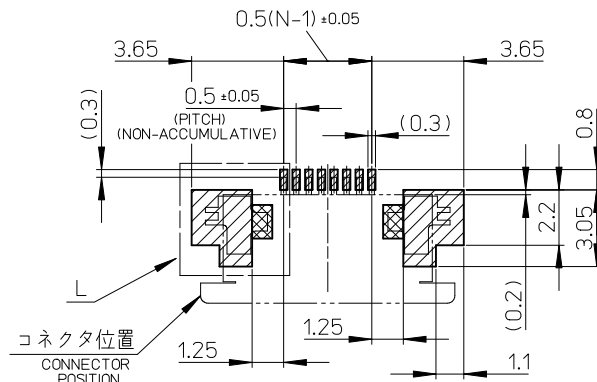
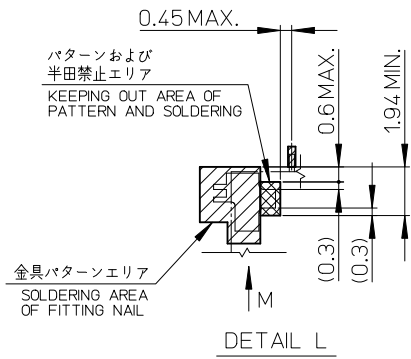
REVISED EC NO. J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:SHIMOMIYAMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	±0.25	M. NABE I	'05/02/14	0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING molex MOLEX INCORPORATED SD-52745-050					
	30 OVER	±0.3	K. TOJO	'05/02/14						
ANGULAR ±3 °		APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		N. UKITA	'05/02/14	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



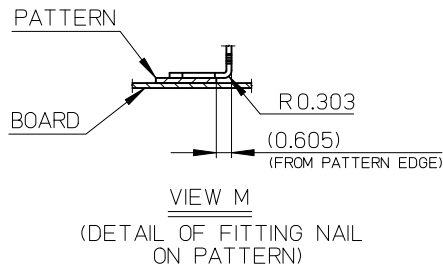
適合金めっきFPC推奨寸法
 APPLICABLE FPC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



適合金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD
 PLATING RECOMMENDED DIMENSION
 仕上がり厚さ: 0.3±0.03
 THICKNESS: 0.3+0.03/-0.03



参考基板レイアウト
 (マウント面)
 RECOMMENDED P.C BOARD
 PATTERN DIMENSION(REF.)
 (MOUNTING SIDE)



VIEW M
 (DETAIL OF FITTING NAIL
 ON PATTERN)

注記NOTES

1.使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
 HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
 アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
 ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
 ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)
 TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING
 金具: リン青銅、ニッケル下地金めっき (t=0.2)
 FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART
 NO.52745-**59 SHOULD BE LOCKED.

3.ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、

基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。

MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM
 DATUM-H.

UPPER DIRECTION: 0.1MAXIMUM

LOWER DIRECTION: 0.15 MAXIMUM

4.偶数極に適用

APPLY FOR EVEN CIRCUIT.

5.ハターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6.R0.3は、FPCの胴体部にかからないこと

R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7.ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

打抜き方向は導体側から補強板を推奨致します。

補強フィルム材質はポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

RECOMMENDED MATERIAL :

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2011-0041 DRWN:HYOSHINO 2010/07/08 CHKD:SHIMOMIYAMA 2010/07/08 APPR:KMORIKAWA 2010/07/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY M. NABE I	DATE '05/02/14	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING			
		10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '05/02/14	MOLEX INCORPORATED			
		30 OVER	± ---	APPROVED BY N. UKITA	DATE '05/02/14				
ANGULAR	± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52745-050	SHEET NO. 2 OF 2			
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							